SCAS779 - SEPTEMBER 2004

- Controlled Baseline

   One Assembly/Test Site, One Fabrication Site
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree<sup>†</sup>
- 4.5-V to 5.5-V V<sub>CC</sub> Operation

<sup>†</sup> Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

#### description/ordering information

Inputs Accept Voltages to 5.5 V

- Max t<sub>pd</sub> of 10 ns at 5 V
- Inputs Are TTL-Voltage Compatible

D PACKAGE (TOP VIEW)									
1A 1B 1Y 2A 2B 2Y GND	1 2 3 4 5 6 7	υ	14 13 12 11 10 9 8		V <sub>CC</sub> 4B 4A 4Y 3B 3A 3Y				

The SN74ACT08 is a quadruple 2-input positive-AND gate. This device performs the Boolean functions  $Y = A \bullet B$  or  $Y = \overline{A} + \overline{B}$  in positive logic.

#### **ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE <sup>‡</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SOIC – D	Tape and reel	SN74ACT08IDREP	SACT08IEP

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

**FUNCTION TABLE** 

INP	UTS	OUTPUT
Α	В	Y
Н	Н	Н
L	Х	L
Х	L	L

## logic diagram, each gate (positive logic)





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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to V <sub>CC</sub> + 0.5 V
Output voltage range, V <sub>O</sub> (see Note 1)	–0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V <sub>CC</sub> or GND	±200 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2)	
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
VI	Input voltage	0	VCC	V
VO	Output voltage	0	VCC	V
IOH	High-level output current		-24	mA
IOL	Low-level output current		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		8	ns/V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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PARAMETER	TEST COI	NULLIONS	TEST CONDITIONS $V_{CC}$						
		VCC	MIN	TYP	MAX	MIN	MAX	UNIT	
	L 50 A		4.5 V	4.4	4.49		4.4		
	I <sub>OH</sub> = –50 μA		5.5 V	5.4	5.49		5.4		
VOH IOF	0.4	4.5 V	3.86			3.76		V	
	I <sub>OH</sub> = -24 mA						4.76		
	I <sub>OH</sub> = -75 mA <sup>†</sup>		5.5 V				3.85		
1 50 A			4.5 V		0.001	0.1		0.1	
	I <sub>OL</sub> = 50 μA		5.5 V		0.001	0.1		0.1	
VOL			4.5 V			0.36		0.44	V
	I <sub>OL</sub> = 24 mA		5.5 V			0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$		5.5 V					1.65	
lj	$V_I = V_{CC} \text{ or } GND$		5.5 V			±0.1		±1	μΑ
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V			2		20	μA
$\Delta I_{CC}^{\ddagger}$	One input at 3.4 V,	Other inputs at GND or $V_{CC}$	5.5 V		0.6			1.5	mA
Ci	VI = V <sub>CC</sub> or GND		5 V		4.5				pF

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

<sup>†</sup>Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

<sup>‡</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm\,$ 0.5 V (unless otherwise noted) (see Figure 1)

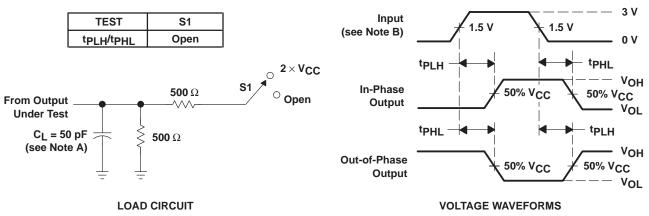
	FROM	то	Τį	λ = 25°C			MAY	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH	A or B	V	1	6.5	9	1	10	
<sup>t</sup> PHL	AOIB	T	1	6.5	9	1	10	ns

## operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = $25^{\circ}$ C

	PARAMETER	TEST	CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance	C <sub>L</sub> = 50 pF,	f = 1 MHz	20	pF



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### PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.
- C. The outputs are measured one at a time, with one input transition per measurement.

#### Figure 1. Load Circuit and Voltage Waveforms



### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins P	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74ACT08IDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04759-01XE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74ACT08-EP :

Catalog: SN74ACT08

• Military: SN54ACT08

NOTE: Qualified Version Definitions:

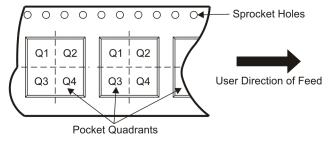
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



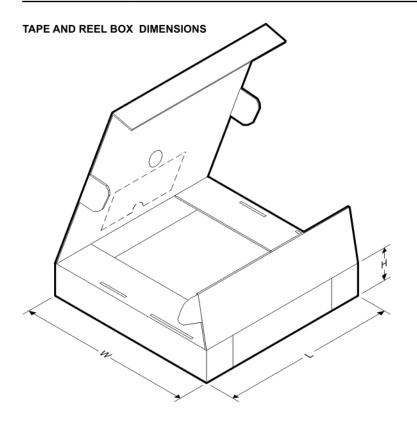
*All dimensions are nominal
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Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT08IDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



## PACKAGE MATERIALS INFORMATION

6-Nov-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT08IDREP	SOIC	D	14	2500	333.2	345.9	28.6

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



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